



# New Design Series

## PRODUCT INFORMATION

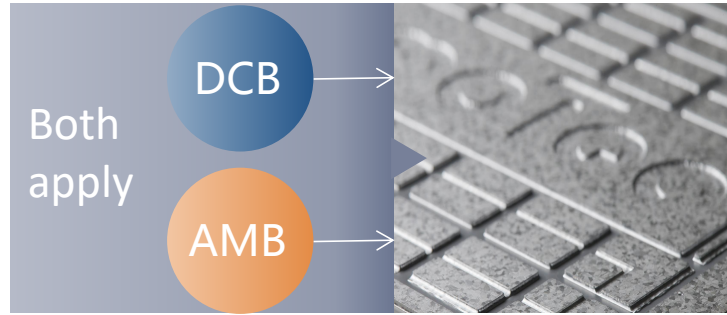
富乐华集团

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# NEW DESIGN SERIES

## 1 Design Properties

- ✓ Available for DCB and AMB Technology
- ✓ Available Cu thickness 0.25mm,0.3mm,0.4mm,0.5mm, 0.8mm
- ✓ Available material  $Al_2O_3$ ,ZTA,AlN,Si<sub>3</sub>N<sub>4</sub> thickness acc. to DCB & AMB design rules



### Direct Copper Bonding

	0.25mm	0.30mm	0.40mm
0.25mm	HP AlN ZTA	ZTA	/
0.32mm	HP ZTA	HP ZTA	ZTA
0.38mm	ST HP AlN	ST HP AlN	/
0.50mm	ST AlN	ST AlN	ST AlN
0.63mm	ST AlN	ST AlN	ST AlN
0.76mm	ST	ST	ST
0.89mm	ST	ST	ST
1.00mm	ST	ST	ST



### Active Metal Brazing

	0.25mm	0.30mm	0.40mm	0.50mm	0.80mm
0.25mm	Si <sub>3</sub> N <sub>4</sub> AlN	Si <sub>3</sub> N <sub>4</sub>	Si <sub>3</sub> N <sub>4</sub>	Si <sub>3</sub> N <sub>4</sub>	Si <sub>3</sub> N <sub>4</sub>
0.32mm	Si <sub>3</sub> N <sub>4</sub>	Si <sub>3</sub> N <sub>4</sub>	Si <sub>3</sub> N <sub>4</sub>	Si <sub>3</sub> N <sub>4</sub>	Si <sub>3</sub> N <sub>4</sub>
0.38mm	AlN	AlN	/	/	/
0.63mm	AlN	AlN	AlN	AlN	/
1.00mm	AlN	AlN	AlN	AlN	AlN

DCB Material:

ST : Al<sub>2</sub>O<sub>3</sub>-ST  
 HP : Al<sub>2</sub>O<sub>3</sub>-HP  
 ALN : AlN Aluminium Nitride  
 ZTA : ZTA Alumina 9% ZrO<sub>2</sub> Doped

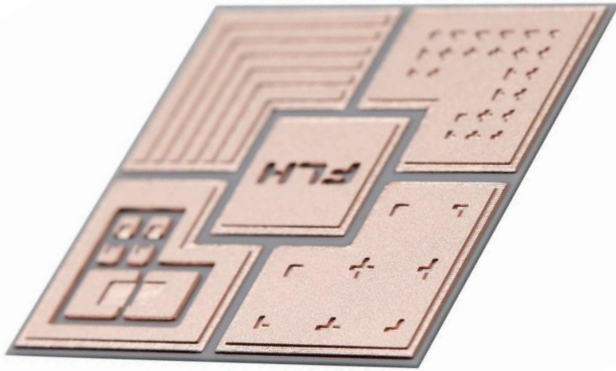
AMB Material:

ALN : AlN Aluminium Nitride  
 Si<sub>3</sub>N<sub>4</sub> : Si<sub>3</sub>N<sub>4</sub> Silicon Nitride

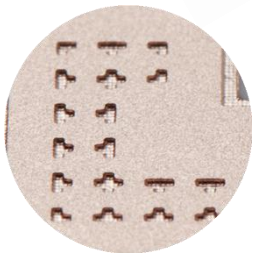
- COPPER THICKNESS
- CERAMIC THICKNESS

# WHAT CAN WE DO BY USING THE NEW DESIGN?

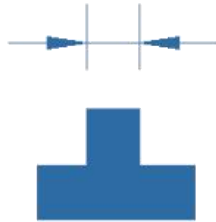
- Someway that we don't want the SMOBC (Solder mask over bare copper)



- Proposed Design Width from 0.3mm – 2mm (For bigger width on request)



Proposed width 0.3-2.0mm



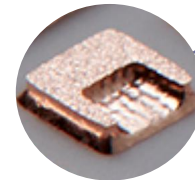
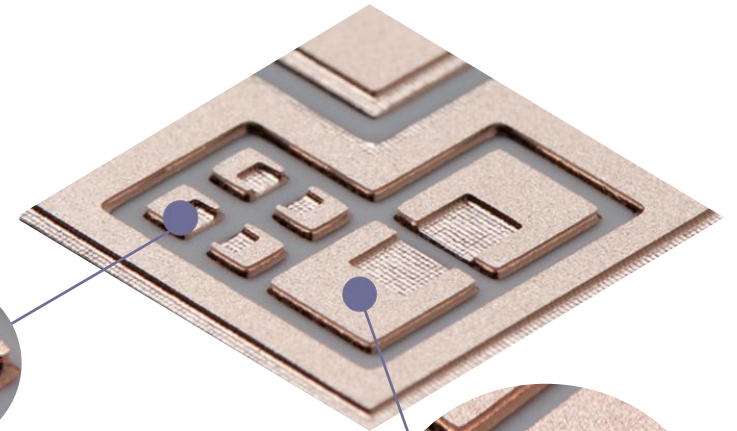
PROFESSIONAL CONFIDENTIALITY



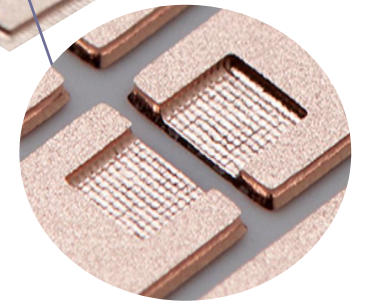
- ◆ Someway we want the parts to be fixed inside.

## Design Customized

- ◆ Current design based on 0.3mm copper



Area size 0.8×0.8mm

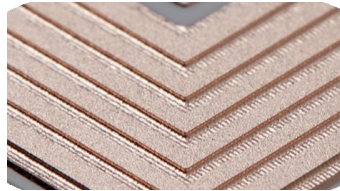


Area size 2.0×1.8mm

# WHAT CAN WE DO BY USING THE NEW DESIGN?

## PATTERNS OF DIFFERENT HEIGHTS

Someway that we want different altitude copper pattern at one side.

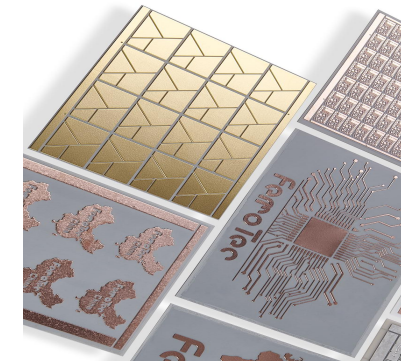
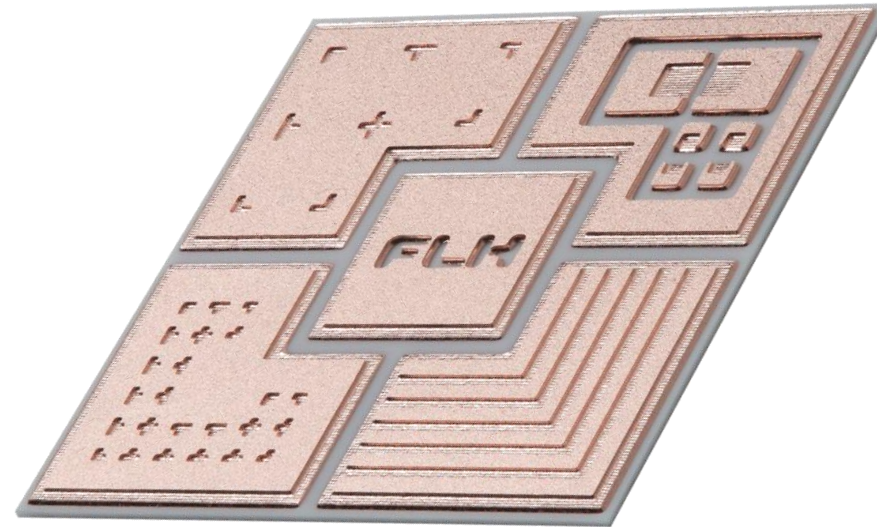


### Design Customized

Current design based on 0.3mm copper, For different pattern design on request.

## APPLICABLE OCCASION

- Add ladder shaped design to the copper edge would increase the reliability effectively.
- Suitable for both DCB and AMB technology



## SPECIFICATION REFERENCE

1. Available Cu thickness 0.25mm,0.3mm,0.4mm,0.5mm,0.8mm
2. Available material  $Al_2O_3$ ,ZTA,AIN, $Si_3N_4$  thickness acc. to DCB & AMB design rules

## RELIABILITY



### Cycling Condition

- -55°C to 150 °C
- 15min at each chamber , transfer time<30s



### Reference Layout

- FLH internal test layout
- 0.3mm copper top & bottom
- With ceramic of 0.32mm ZTA / Si<sub>3</sub>N<sub>4</sub> 、 0.38mm Al<sub>2</sub>O<sub>3</sub> and 0.635mm AlN

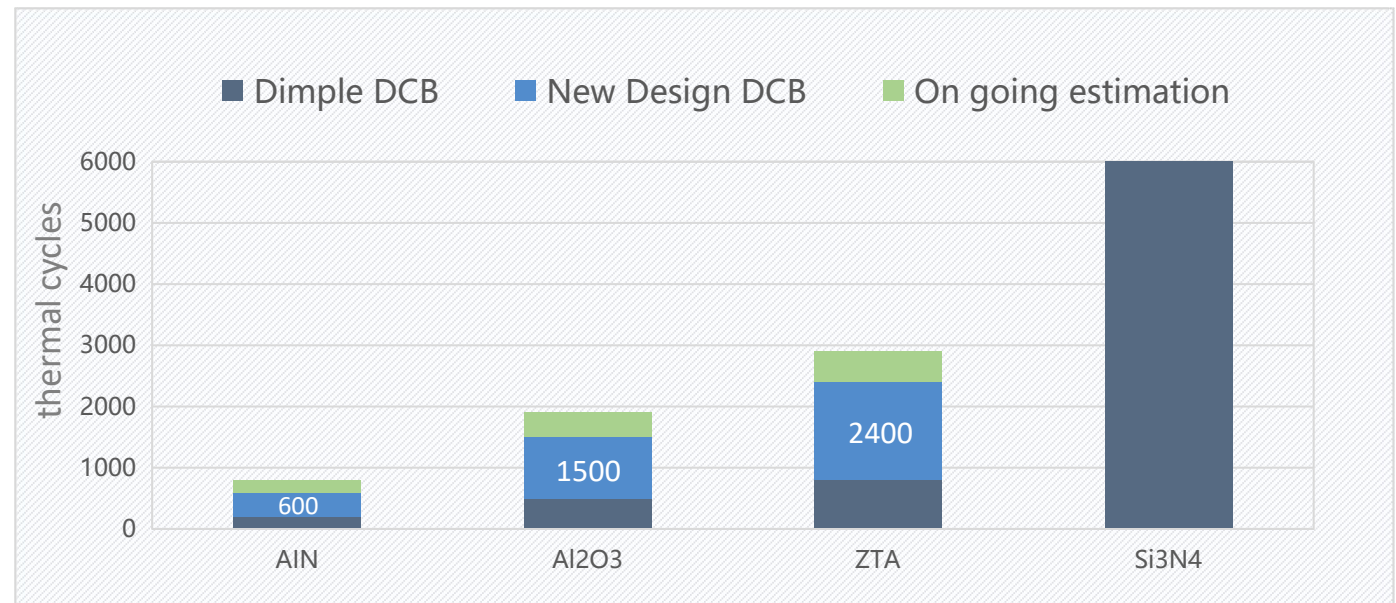
With the ladder copper edge design shows an excellent performance advantage on lifetime test, Current lifetime shows close to 3 times better than with dimples, cycling test are still on going.



### Partial test data



Note : Tests are based on FLH internal test layout; Different pattern layout may influence the result



THANKS FOR WATCHING!

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Ferrotec |  FLH

Shanghai:86 21 36161010 Jiangsu:86 0515 85712888



@ FLH reserves all right of interpretation.